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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 35010.1-2018

**Semiconductor die products -- Part 1: Requirements for
procurement and use**

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Foreword

GB/T 35010 "Semiconductor Chip Products" is divided into the following parts.

- Part 1. Procurement and use requirements;
- Part 2. Data exchange format;
- Part 3. Guidelines for handling, packaging and storage;
- Part 4. Chip user and supplier requirements;
- Part 5. Electrical Simulation Requirements;
- Part 6. Thermal Simulation Requirements;
- Part 7. XML format for data exchange;
- Part 8. EXPRESS format for data exchange.

This part is the first part of GB/T 35010.

This section uses the translation method equivalent to the use of IEC 62258-1.2009 "semiconductor chip products Part 1. procurement and use."

The Chinese documents that have a consistent correspondence with the normatively quoted international documents in this section are as follows.

- GB/T 2900 (all parts) Electrical terminology [IEC 60050 (all parts)]
- GB/T 35010.2-2018 Semiconductor chip products Part 2. Data exchange format (IEC 62258-2.2011, IDT)
- GB/T 35010.4-2018 Semiconductor chip products Part 4. Chip user and supplier requirements (IEC /TR 62258-4.2012, IDT)
- GB/T 35010.5-2018 Semiconductor chip products - Part 5. Electrical simulation requirements (IEC 62258-5.2006, IDT)
- GB/T 35010.6-2018 Semiconductor chip products - Part 6. Thermal simulation

requirements (IEC 62258-6.2006, IDT)

---GB/T 35010.7-2018 Semiconductor chip products Part 7. XML format for data exchange (IEC /T R62258-

7.2007, IDT)

---GB/T 35010.80.8-2018 Semiconductor chip products - Part 8. EXPRESS format for data exchange (IEC /TR

62258-8.2008,IDT)

This section also made the following editorial changes.

--- Taking into account the adaptation of China's standard system, the name will be changed to "Semiconductor chip products Part 1. Procurement and use requirements";

--- Appendix B. B.1 is the name of a foreign standard organization. It has nothing to do with this standard. It only retains the title.

1 Scope

This part of GB/T 35010 is used to guide the production, supply and use of semiconductor chip products. Semiconductor chip products include.

- * Wafers;
- * Single bare chip;
- * Chips and wafers with interconnect structures;
- * Small or partially packaged chips and wafers.

This section defines the minimum requirements for the data required for this type of chip product and also contributes to the design and procurement of chip-containing component products. It contains

The requirements for data are covered as follows.

- * product identification;
- * Product data;
- * Chip mechanical information;
- * Test, quality, assembly and reliability information;
- * Process, transport, and store information.

This section includes specific data used to describe the geometric, physical, and connection method data of the chip during R&D and manufacturing.

Claim. Refer to Appendix A and Appendix B for related vocabularies and abbreviations.

2 Normative references

The following documents are indispensable for the application of this document. For dated references, only dated versions apply to this article

Pieces. For undated references, the latest version (including all amendments) applies to this document.

GB/T 25915.1-2010 Cleanrooms and related controlled environments - Part 1. Air cleanliness level (ISO 14644-1.1999,

IDT)

IEC 60050 (all parts) Electrotechnical terminology (International electrotechnical vocabulary)

IEC 60191 (all parts) Mechanical standardization of semiconductor devices (Mechanical standardization of semiconductor Devices)

IEC 60191-4.1999 Mechanical standardization of semiconductor devices - Part 4. Semiconductor device package outline coding and classification

(Mechanical standardization of semiconductor devices - Part 4. Coding system and classification into

Forms of package outlines for semiconductor device packages)

Amendment 1 (2001) Amendment 2 (2002)

IEC 61360-1 Standard data element types and related classification schemes for electrical components - Part 1. Definitions - Principles and methods

(Standard data element types with associated classification scheme for electric components - Part 1.

Definitions - Principles and methods)

IEC 62258-2 Semiconductor chip products Part 2. Data interchange formats (Semiconductor die products - Part 2.

Exchanged data formats)

IEC / T R 62258-3 Semiconductor Chip Product Part 3. Guidelines for Handling, Packaging and Storage (Semiconductor die prod-

ucts - Part 3. Recommendations for good practice in handling, packing and storage)